SELECTION GUIDE FOR SOLDER PASTE

	SOLDER PASTE			
Product Features	**Alloy Compatibility**	**63/37**	**SAC0307**	**SAC305**
	Applications	Specially formulated for Fine Pitch Surface Mount application where application pitch could be as fine as 12 mils pitch.	Hiflo solder paste was developed to have better wettability in reflow soldering process. It is cost effective while shows comparable mechanical strength with SAC305.	Developed to have better wettability in reflow process. This alloy is designed to be substituted for Tin/Lead in all electronics assembly soldering operations.
	Powder Type	Type 4	Type 4	Type 4, Type 5
Flux	**Type 3 (24-45μm)**	On Request	-	-
	Type 4 (20-38μm)	11.0 ± 1.0 wt%	11.5 ± 0.5 wt%	11.5 ± 1.0 wt%
	Type 5 (15-25μm)	-	-	12.0 ± 1.0 wt%
Properties	**Viscosity** IPC-TM-650 2.4.34	750 ± 250 KcPs	750 ± 250 KcPs	750 ± 250 KcPs
	Tackiness JIS Z 3284 Annex 9	>24 hrs (>100gf)	>24 hrs (>100gf)	>24 hrs (>100gf)
	Slump Test JIS Z 3284 Annex 7, Annex 8	No Slump Observed	No Slump Observed	No Slump Observed
	Solder Ball Test JIS Z 3284 Annex 11	Passed	Passed	Passed
	Residue Dryness Test JIS Z 3284 Annex 12	Passed	Passed	Passed
	Halide Content JIS Z 3197 8.1.4.2.1	Not Added	Not Added	Not Added
	Halogen Content EN14582	Not Detected	Not Detected	Not Detected
	SIR **(85˚C, 85%RH, 168hrs)** IPC-TM-650 2.6.3.3	>1 x 10^8 Ω	>1 x 10^8 Ω	>1 x 10^8 Ω
	ECM **(85˚C,88.5%RH,596hr)** IPC-TM-650 2.6.14.1	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth	>1 x 10^8 Ω No Dentrite Growth
	Flux Activity Classification IPC J-STD-004	ROL0	ROL0	ROL0
	Residue Removal	Not Required	Not Required	Not Required
	Stencil Life	At least 24 hrs	At least 24 hrs	At least 24 hrs
	Reflow Peak Temperature ˚C	≥ 205	≥ 240	≥ 235